

# Hyperfast Rectifier, 5 A FRED Pt®

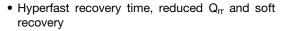




TO-252AA (D-PAK)

PRODUCT SUMMARY					
Package	TO-252AA (D-PAK)				
I <sub>F(AV)</sub>	5 A				
$V_{R}$	600 V				
V <sub>F</sub> at I <sub>F</sub>	1.2 V				
t <sub>rr</sub> (typ.)	18 ns				
$T_J$ max.	175 °C				
Diode variation	Single die				

#### **FEATURES**





RoHS

COMPLIANT **HALOGEN** 

FREE

• 175 °C maximum operating junction temperature

• For PFC CRM/CCM operation

Low forward voltage drop

· Low leakage current

• Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

· Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

#### **DESCRIPTION / APPLICATIONS**

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Peak repetitive reverse voltage	$V_{RRM}$		600	V		
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 150 °C	5			
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	70	Α		
Peak repetitive forward current	I <sub>FM</sub>	T <sub>C</sub> = 150 °C, f = 20 kHz, d = 50 %	10			
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C		

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS MIN. TYP. MA					
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	600	-	-		
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 5 A	-	1.54	1.85	V	
	VF	I <sub>F</sub> = 5 A, T <sub>J</sub> = 150 °C	-	1.20	1.40	1	
Devenue le else en en un ent	1	V <sub>R</sub> = V <sub>R</sub> rated	-	-	5		
Reverse leakage current I <sub>R</sub>		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	130	μA	
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	3.5	-	pF	
Series inductance	LS	Measured lead to lead 5 mm from package body	-	8	-	nH	



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 10$	$00 \text{ A/}\mu\text{s}, V_{\text{R}} = 30 \text{ V}$	ı	18	25		
Reverse recovery time		$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	22	-		
neverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 5 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 390 V	-	25	-	ns	
		T <sub>J</sub> = 125 °C		-	35	-		
Dools recovery ourrent	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	3.9	-	А	
Peak recovery current		T <sub>J</sub> = 125 °C		-	5.1	-		
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	51	-	nC	
		T <sub>J</sub> = 125 °C		-	93	-		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C	
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	-	3	°C/W	
A managina at a consider				0.3		g	
Approximate weight			0.01		oz.		
Marking device		Case style TO-252AA (D-PAK)	5EWH06FN				

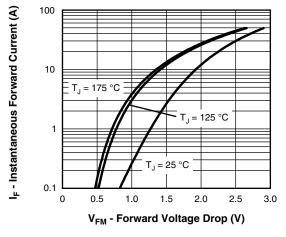


Fig. 1 - Typical Forward Voltage Drop Characteristics

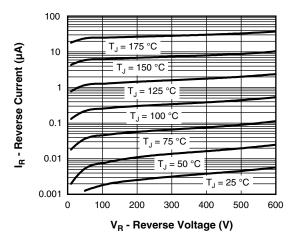


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

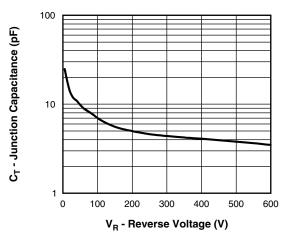


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

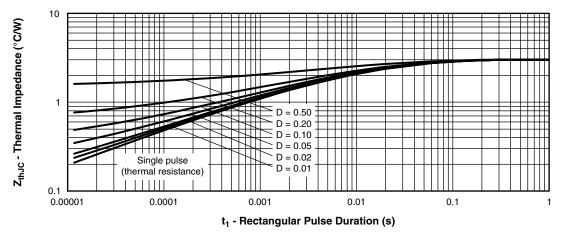


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

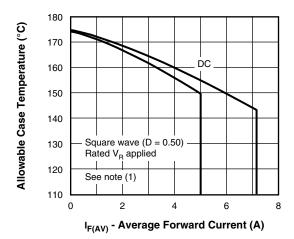


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

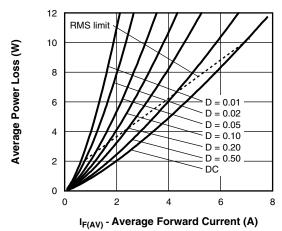


Fig. 6 - Forward Power Loss Characteristics

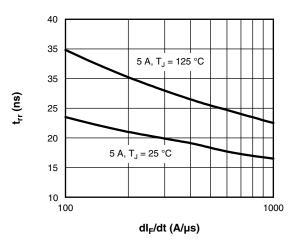


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

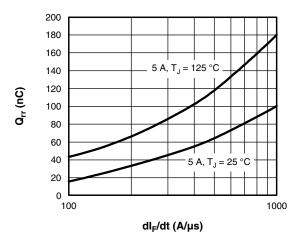


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D)}; I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$ 

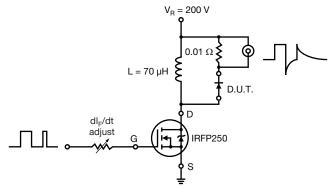
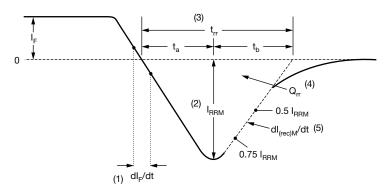


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\rm Q_{rr}$  area under curve defined by  $\rm t_{rr}$  and  $\rm I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

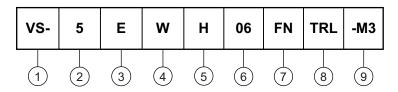
(5)  $dI_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 10 - Reverse Recovery Waveform and Definitions



#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Current rating (5 = 5 A)

3 - Circuit configuration:

E = single diode

4 - Package identifier:

W = D-PAK

H = hyperfast recovery

6 - Voltage rating (06 = 600 V)

7 - FN = TO-252AA

8 - • None = tube

• TR = tape and reel

• TRL = tape and reel (left oriented)

• TRR = tape and reel (right oriented)

9 - Environmental digit:

-M3 = halogen-free, RoHS-compliant and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-5EWH06FN-M3	75	3000	Antistatic plastic tube				
VS-5EWH06FNTR-M3	2000	2000	13" diameter reel				
VS-5EWH06FNTRL-M3	3000	3000	13" diameter reel				
VS-5EWH06FNTRR-M3	3000	3000	13" diameter reel				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95627				
Part marking information	www.vishay.com/doc?95176				
Packaging information	www.vishay.com/doc?95033				
SPICE model	www.vishay.com/doc?95186				



## D-PAK (TO-252AA) "M"

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INCHES		NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	1	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STINIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090 BSC		
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020	BSC	
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA



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